

## Product specifications

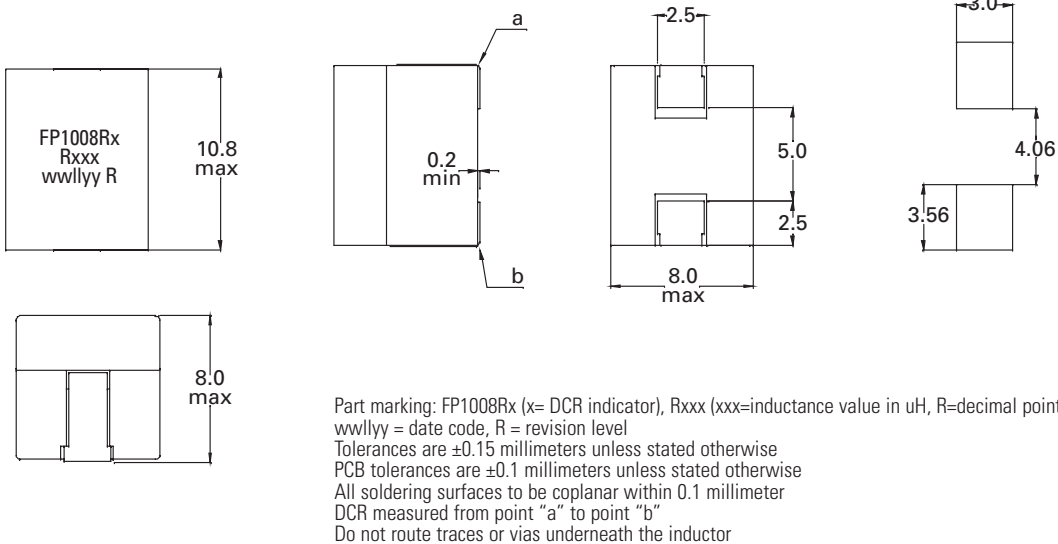
Part Number <sup>9</sup>	OCL <sup>1</sup> (nH)±10%	FLL <sup>2</sup> (nH) minimum	I <sub>rms</sub> <sup>3</sup> (amps)	I <sub>sat</sub> 1 <sup>4</sup> (amps)	I <sub>sat</sub> 2 <sup>5</sup> (amps)	I <sub>sat</sub> 3 <sup>6</sup> (amps)	DCR (mΩ) ±5% @ 20°C	K-factor <sup>7</sup>
<b>R1 version</b>								
FP1008R1-R120-R	120	86	79	112	92	84	0.17	342
FP1008R1-R150-R	150	108	79	90	72	67	0.17	342
FP1008R1-R180-R	180	130	79	74	60	54	0.17	342
FP1008R1-R220-R	220	158	79	56	44	42	0.17	342
FP1008R1-R270-R	270	194	79	44	34	32	0.17	342
FP1008R1-R300-R	300	216	79	38	30	28	0.17	342
<b>R2 version</b>								
FP1008R2-R120-R	120	86	74	112	92	84	0.18	342
FP1008R2-R150-R	150	108	74	90	72	67	0.18	342
FP1008R2-R180-R	180	130	74	74	60	54	0.18	342
FP1008R2-R220-R	220	158	74	56	44	42	0.18	342
FP1008R2-R270-R	270	194	74	44	34	32	0.18	342
FP1008R2-R300-R	300	216	74	38	30	28	0.18	342

1. Open Circuit Inductance (OCL) Test Parameters: 100kHz, 0.1V<sub>rms</sub>, 0.0Adc, +25°C
2. Full Load Inductance (FLL) Test Parameters: 100kHz, 0.1V<sub>rms</sub>, I<sub>sat</sub>1, +25°C
3. I<sub>rms</sub>: DC current for an approximate temperature rise of 40°C without core loss. Derating is necessary for AC currents. PCB layout, trace thickness and width, air-flow, and proximity of other heat generating components will affect the temperature rise. It is recommended that the temperature of the part not exceed 125°C under worst case operating conditions verified in the end application.
4. I<sub>sat</sub>1: Peak current for approximately 20% rolloff @ +25°C
5. I<sub>sat</sub>2: Peak current for approximately 20% rolloff @ +100°C
6. I<sub>sat</sub>3: Peak current for approximately 20% rolloff @ +125°C
7. K-factor: Used to determine B<sub>pp</sub> for core loss (see graph).  
B<sub>pp</sub> = K \* L \* ΔI \* 10<sup>-3</sup>. B<sub>pp</sub> (Gauss), K: (K-factor from table),  
L: (Inductance in nH), ΔI (Peak-to-peak ripple current in Amps).
8. Part Number Definition: FP1008Rx-Rxxx-R  
FP1008 R= Product code and size  
x = DCR indicator  
Rxxx = Inductance value in μH, R = decimal point  
- R suffix = RoHS compliant

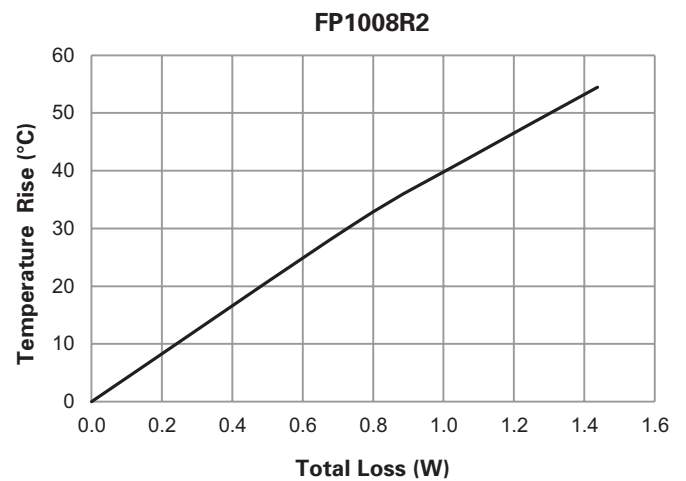
## Dimensions (mm)

### Recommended Pad Layout

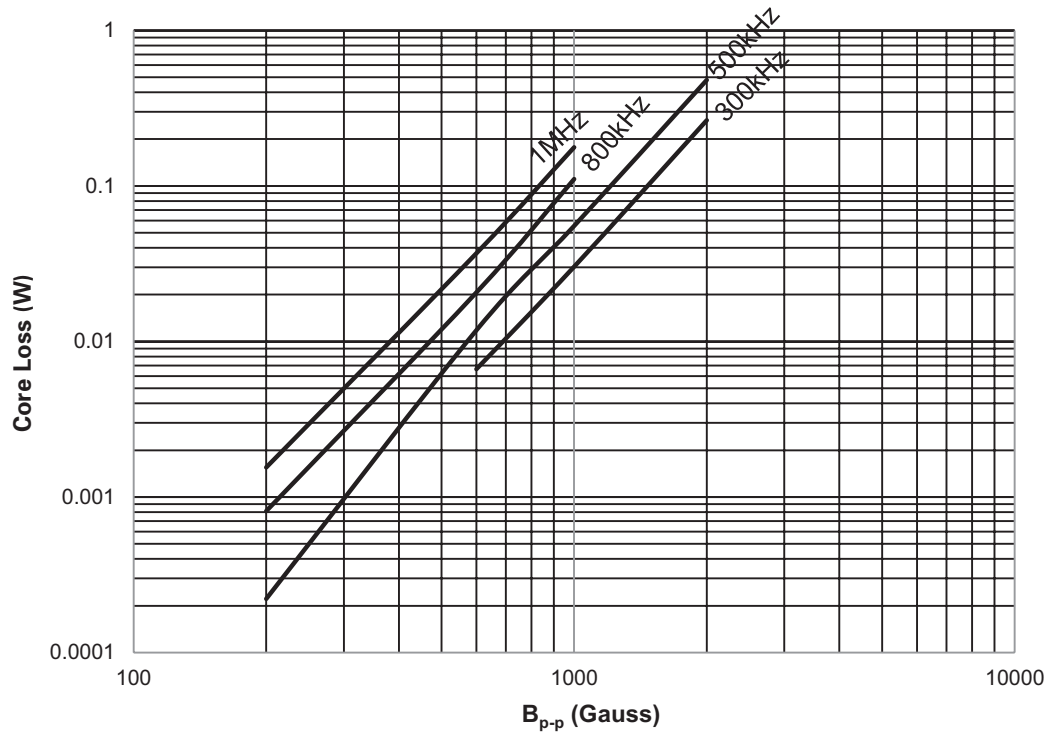
### Schematic



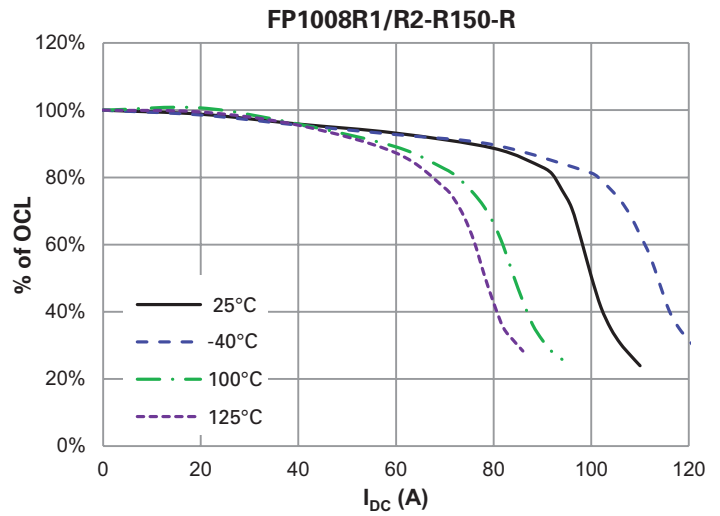
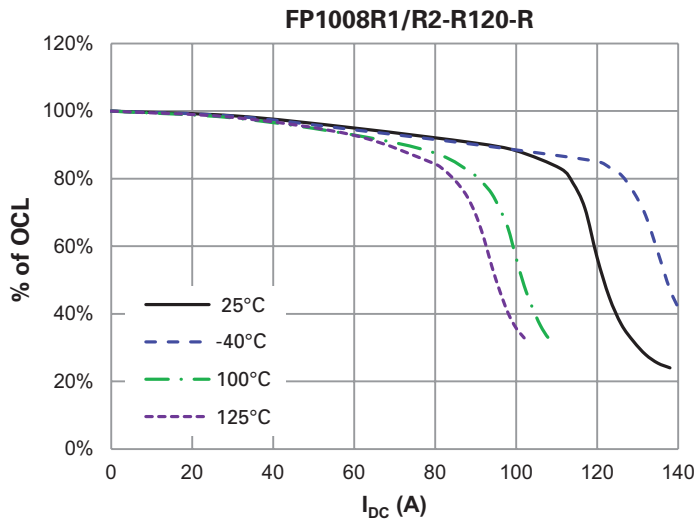
Supplied in tape and reel packaging, 500 parts per 13" diameter reel.



### Core loss vs. Bp-p

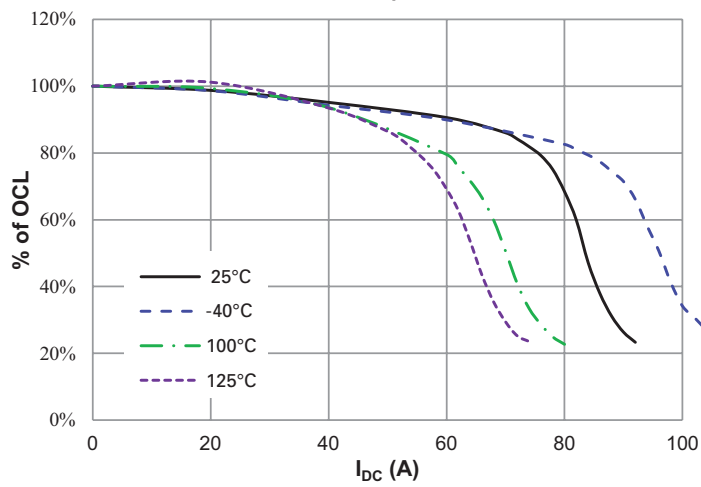


### Inductance characteristics

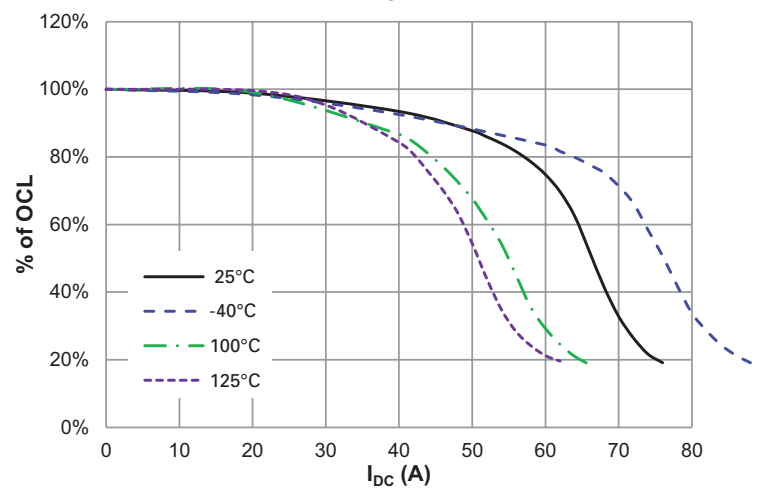


# Inductance characteristics

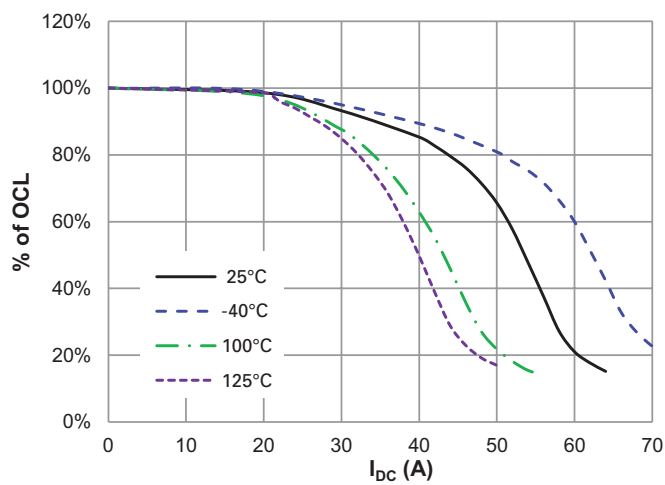
**FP1008R1/R2-R180-R**



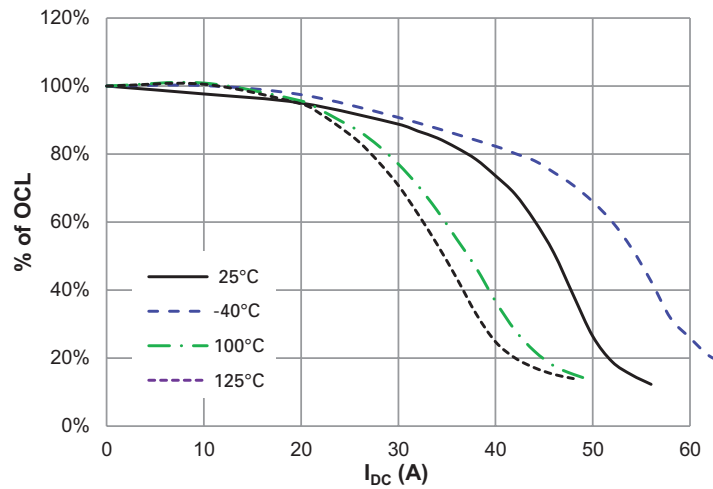
**FP1008R1/R2-R220-R**



**FP1008R1/R2-R270-R**



**FP1008R1/R2-300-R**



## Solder reflow profile

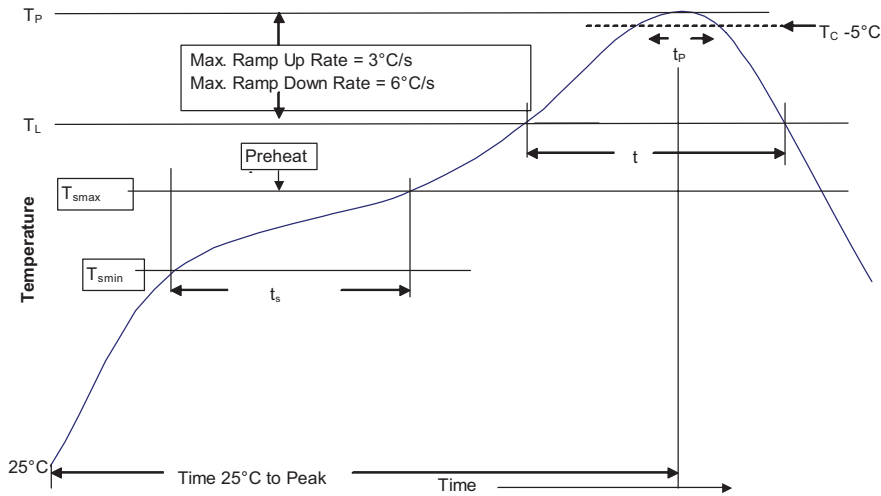


Table 1 - Standard SnPb Solder ( $T_C$ )

Package Thickness	Volume mm <sup>3</sup> <350	Volume mm <sup>3</sup> ≥350
<2.5mm)	235°C	220°C
≥2.5mm	220°C	220°C

Table 2 - Lead (Pb) Free Solder ( $T_C$ )

Package Thickness	Volume mm <sup>3</sup> <350	Volume mm <sup>3</sup> 350 - 2000	Volume mm <sup>3</sup> >2000
<1.6mm	260°C	260°C	260°C
1.6 – 2.5mm	260°C	250°C	245°C
>2.5mm	250°C	245°C	245°C

## Reference JDEC J-STD-020D

Profile Feature	Standard SnPb Solder	Lead (Pb) Free Solder
Preheat and Soak		
• Temperature min. ( $T_{smin}$ )	100°C	150°C
• Temperature max. ( $T_{smax}$ )	150°C	200°C
• Time ( $T_{smin}$ to $T_{smax}$ ) ( $t_s$ )	60-120 Seconds	60-120 Seconds
Average ramp up rate $T_{smax}$ to $T_p$	3°C/ Second Max.	3°C/ Second Max.
Liquidous temperature ( $T_L$ )	183°C	217°C
Time at liquidous ( $t_L$ )	60-150 Seconds	60-150 Seconds
Peak package body temperature ( $T_p$ )*	Table 1	Table 2
Time ( $t_p$ )** within 5 °C of the specified classification temperature ( $T_C$ )	20 Seconds**	30 Seconds**
Average ramp-down rate ( $T_p$ to $T_{smax}$ )	6°C/ Second Max.	6°C/ Second Max.
Time 25°C to Peak Temperature	6 Minutes Max.	8 Minutes Max.

\* Tolerance for peak profile temperature ( $T_p$ ) is defined as a supplier minimum and a user maximum.

\*\* Tolerance for time at peak profile temperature ( $t_p$ ) is defined as a supplier minimum and a user maximum.

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